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CONSTANT FILMS
INVENTOR: DAVID CHEUNG, ET AL.
EXPRESS MAIL NO.:EV335470158US PAGE 1 OF 10 PAGE 1 OF 10

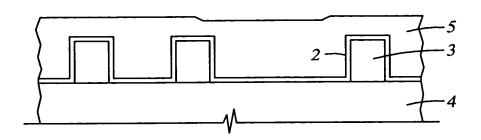


Fig. 1A (PRIOR ART)

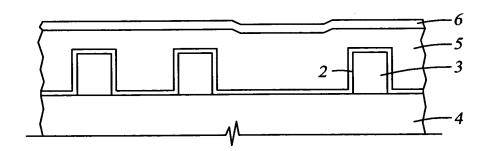
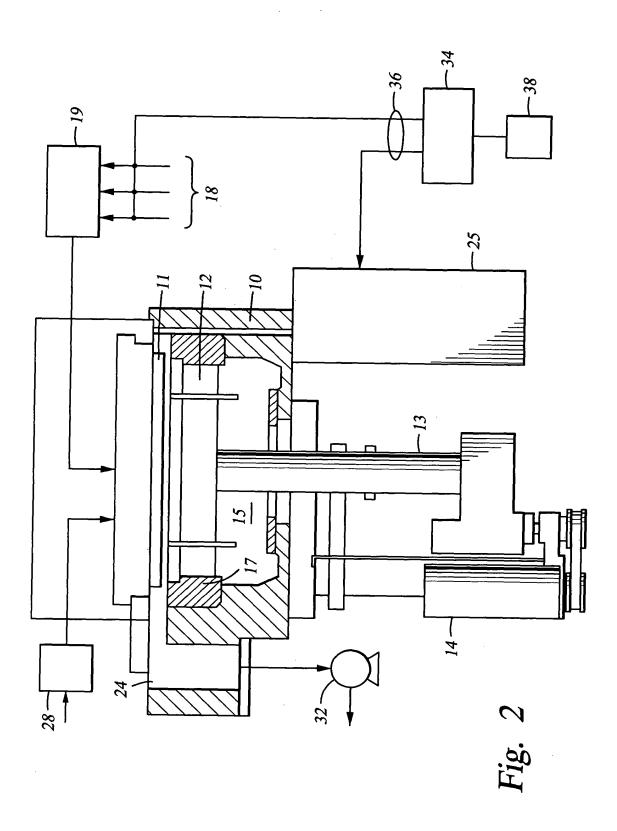


Fig. 1B (PRIOR ART)

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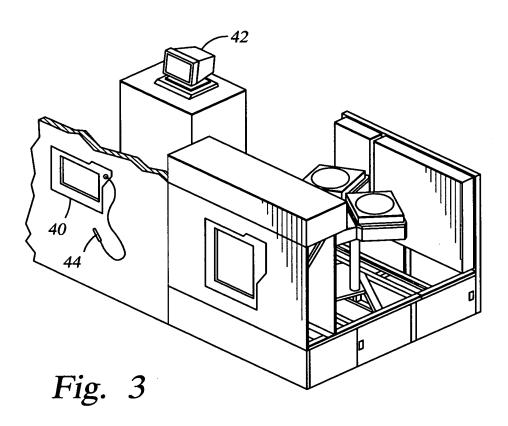
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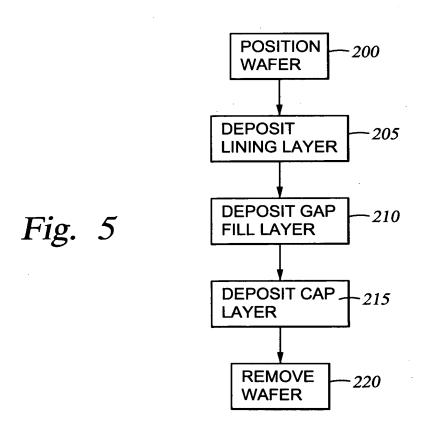


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INVENTOR: DAVID CHEUNG, ET AL.

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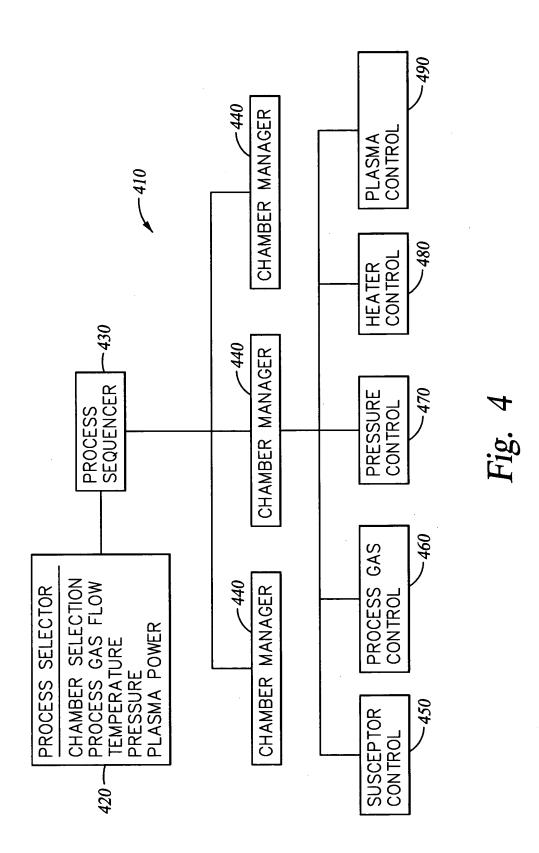
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PLASMA PROCESSES FOR DEPOSITING LOW DIELECTRIC

CONSTANT FILMS
INVENTOR: DAVID CHEUNG, ET AL.
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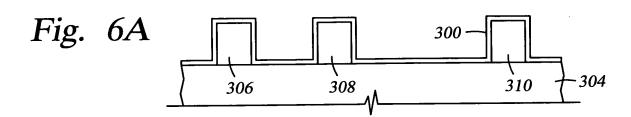
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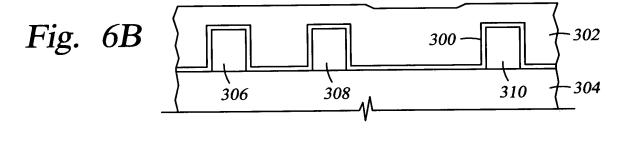
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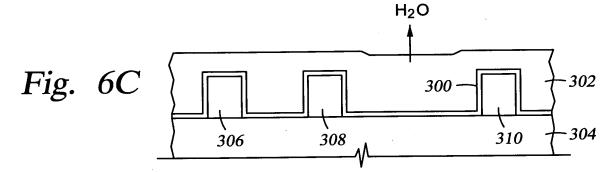
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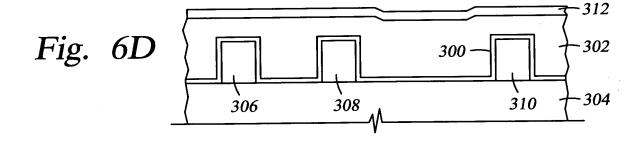
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INVENTOR: DAVID CHEUNG, ET AL.
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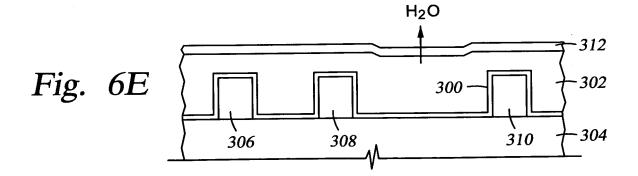
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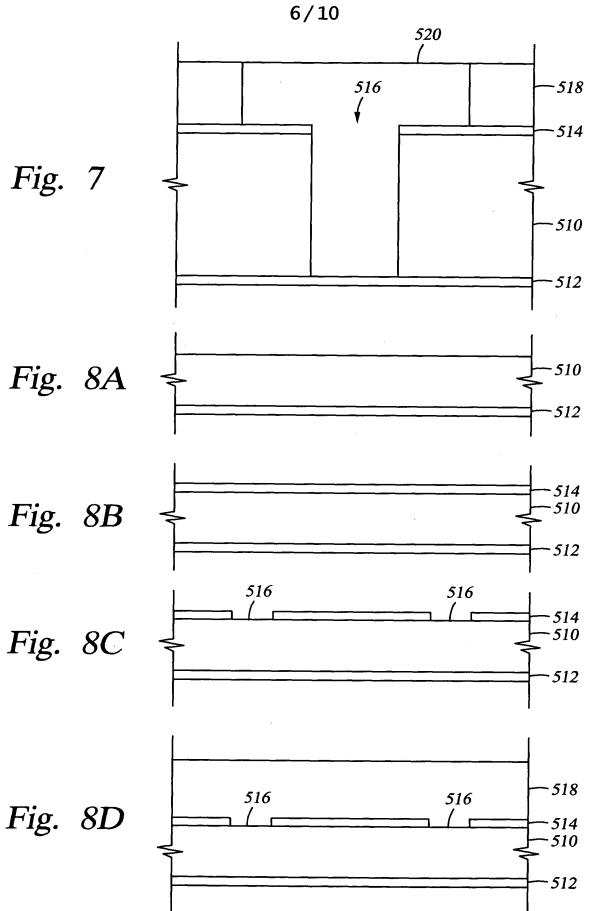


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INVENTOR: DAVID CHEUNG, ET AL.

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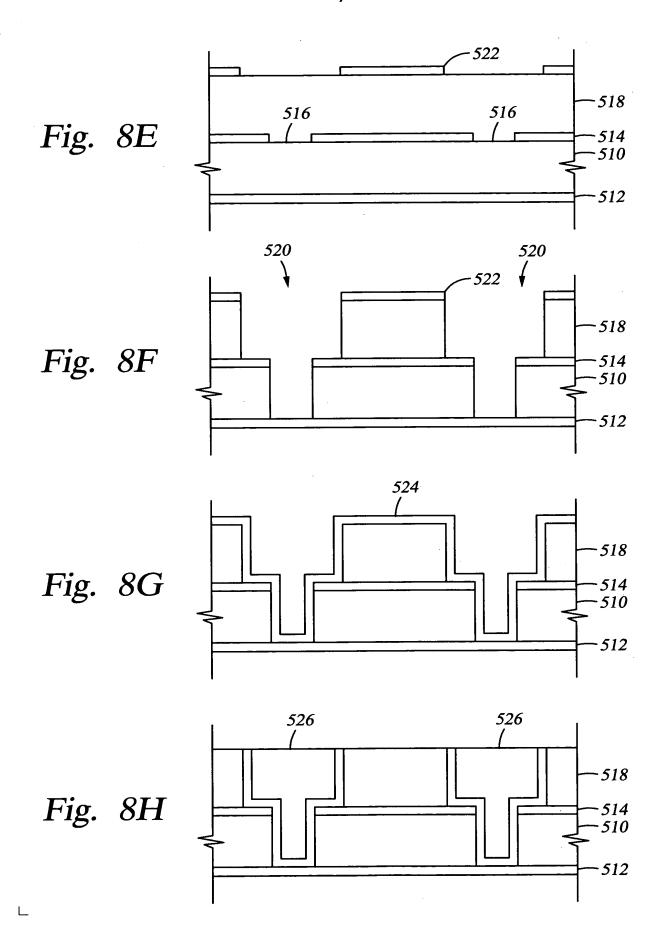
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DAVID CHEUNG, ET AL.

INVENTOR: PAGE 70F 10 EXPRESS MAIL No.: EV335470158US

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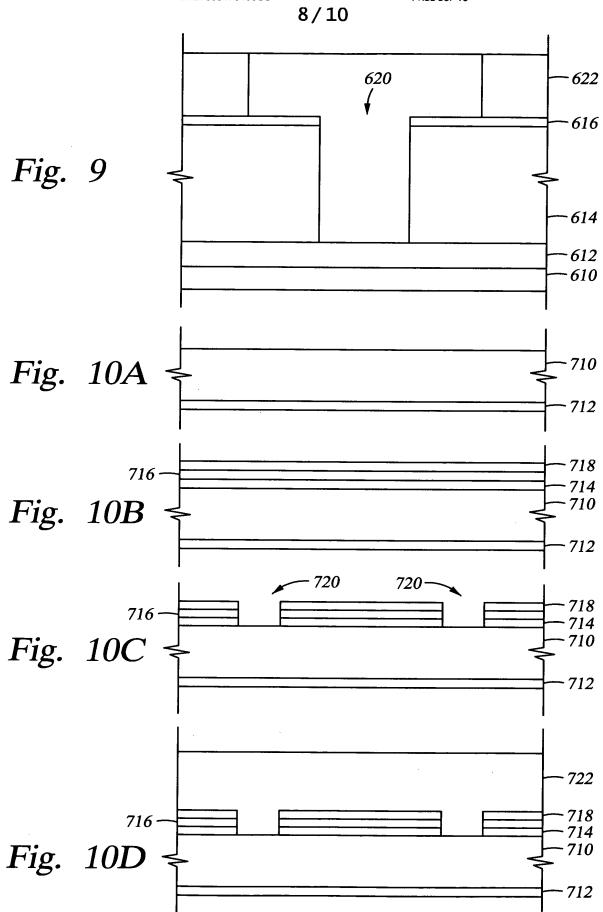
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INVENTOR: DAVID CHEUNG, ET AL. EXPRESS MAIL NO.: EV335470158US

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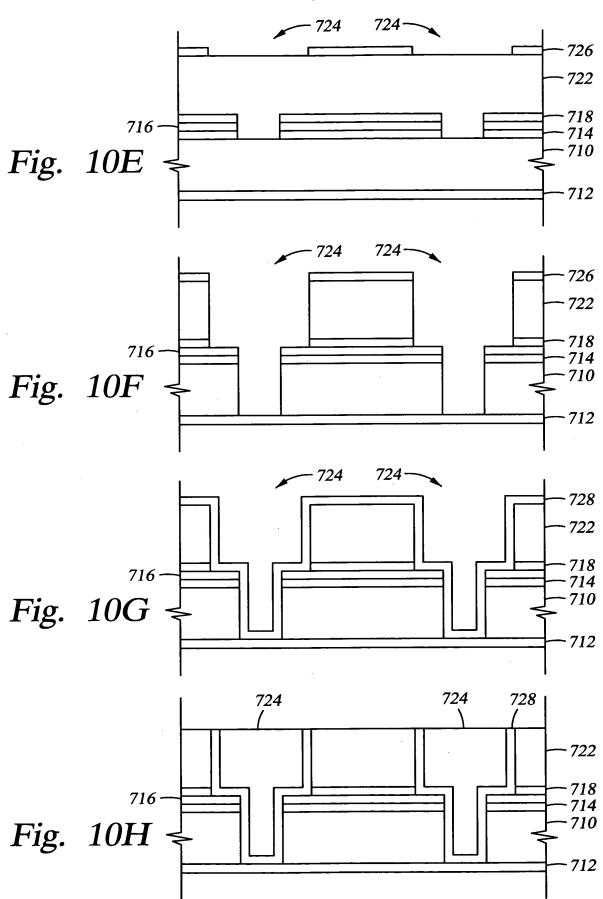
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